

**REMARKS**

The Office Action mailed on May 8, 2003, has been received and reviewed.

Claims 1 through 9, 11 through 14, and 16 through 21 are currently pending and under consideration in the above-referenced application. Each of claims 1 through 9, 11, 12, 14, and 16 through 21 stands rejected.

The indication that claims 2, 3, and 13 recite allowable subject matter is gratefully acknowledged.

Reconsideration of the above-referenced application is respectfully requested.

**Rejections Under 35 U.S.C. § 112, Second Paragraph**

Claims 2 through 4 stand rejected under 35 U.S.C. § 112, second paragraph, for being indefinite. In particular, each of claims 2 through 4 recites “said semiconductor die,” an element for which claim 1, prior to the amendment thereof, did not provide sufficient antecedent basis. As independent claim 1 has been revised to replace the element “semiconductor device” with “semiconductor die,” it is respectfully submitted that independent claim 1 now provides sufficient antecedent basis for the recitation of “said semiconductor die” in claims 2 through 4 and, thus, that each of claims 2 through 4 complies with the definiteness requirement of 35 U.S.C. § 112, second paragraph.

Claim 21 has been rejected for reciting “the semiconductor device,” an element which lacks antecedent basis. Claim 21 has been revised to replace the recitation of “the semiconductor device” with “the semiconductor die,” an element for which antecedent basis is provided in independent claim 12. Accordingly, it is respectfully submitted that claim 21 complies with the definiteness requirement of 35 U.S.C. § 112, second paragraph.

For these reasons, it is respectfully requested that the 35 U.S.C. § 112, second paragraph, rejections of claims 2 through 4 and 21 be withdrawn.

### **Obviousness-Type Double Patenting Rejections**

Claims 1, 7, 8, 11, 12, 16, 17, 19, and 20 stand rejected under the judicially created doctrine of obviousness-type double patenting as being unpatentable over claims 15, 16, 24, 25, 32, and 33 of U.S. Patent 6,144,560.

Claims 4, 6, and 21 have been rejected under the judicially created doctrine of obviousness-type double patenting as being unpatentable over claims 15, 24 and 32 of U.S. Patent 6,144,560, in view of U.S. Patent 5,236,372 to Yunoki et al. (hereinafter “Yunoki”).

Claims 5 and 18 stand rejected under the judicially created doctrine of obviousness-type double patenting as being unpatentable over claims 15, 24, and 32 of U.S. Patent 6,144,560, in view of U.S. Patent 6,072,236 to Akram et al (hereinafter “Akram”).

Claim 9 is rejected under the judicially created doctrine of obviousness-type double patenting as being unpatentable over claims 15, 24, and 32 of U.S. Patent 6,144,560, in view of Yunoki.

Claim 14 has been rejected under the judicially created doctrine of obviousness-type double patenting as being unpatentable over claims 15, 24, and 32 of U.S. Patent 6,144,560, in view of Yunoki.

Claims 1, 7, 8, 11, 12, and 16 have been rejected under the judicially created doctrine of obviousness-type double patenting as being unpatentable over claims 9, 10, 17, 18, 26, 27, 34, and 35 of U.S. Patent 6,295,209.

Claims 4, 6, and 21 stand rejected under the judicially created doctrine of obviousness-type double patenting as being unpatentable over claims 9, 17, 26, and 34 of U.S. Patent 6,295,209, in view of Yunoki.

Claims 5 and 18 have been rejected under the judicially created doctrine of obviousness-type double patenting as being unpatentable over claims 9, 17, 26, and 34 of U.S. Patent 6,295,209, in view of Akram.

Claim 9 stands rejected under the judicially created doctrine of obviousness-type double patenting as being unpatentable over claims 9, 17, 26, and 34 of U.S. Patent No. 6,295,209, in view of Yunoki.

Claim 14 is rejected under the judicially created doctrine of obviousness-type double patenting as being unpatentable over claims 9, 17, 26, and 34 of U.S. Patent No. 6,295,209, in view of Yunoki.

Terminal disclaimers and the appropriate fees are being filed herewith, in compliance with 37 C.F.R. § 1.321(b) and (c), to obviate the obviousness-type double patenting rejection, thereby expediting prosecution of the above-referenced application and avoiding further expense and time delay. The filing of the terminal disclaimers in the above-referenced application should not be construed as acquiescence of the obviousness-type double patenting rejections.

#### **Rejections Under 35 U.S.C. § 103(a)**

Claims 1, 6 through 9, and 11 are rejected under 35 U.S.C. § 103(a) as being unpatentable over the teachings of Yunoki, in view of teachings from U.S. Patent 4,303,291 to Dines (hereinafter “Dines”) and U.S. Patent 5,386,087 to Lee et al (hereinafter “Lee”).

M.P.E.P. 706.02(j) sets forth the standard for a Section 103(a) rejection:

To establish a *prima facie* case of obviousness, three basic criteria must be met. First, there must be some suggestion or motivation, either in the references themselves or in the knowledge generally available to one of ordinary skill in the art, to modify the reference or combine reference teachings. Second, there must be a reasonable expectation of success. Finally, the prior art reference (or references when combined) must teach or suggest all the claim limitations. The teaching or suggestion to make the claimed combination and the reasonable expectation of success must both be found in the prior art, and not based on applicant’s disclosure. *In re Vaeck*, 947 F.2d 488, 20 USPQ2d 1438 (Fed. Cir. 1991).

As noted in the outstanding Office Action, the teachings of Yunoki, Dines, and Lee are drawn to circuit boards which include terminals adjacent to an edge thereof. The terminals of the circuit boards that are taught in each of these references are exposed through and laterally surrounded by a protective layer.

In contrast to the subject matter taught in Yunoki, Dines, and Lee, independent claim 1, as amended and presented herein, recites a semiconductor device which includes a semiconductor die with at least one bond pad positioned on a surface thereof and adjacent an

edge thereof, as well as a layer comprising polymer on at least a portion of the surface. The layer has a notch formed therein which exposes at least a portion of the at least one bond pad.

As none of Yunoki, Dines, or Lee teaches or suggests a semiconductor die with bond pads at an edge thereof and a protective layer thereon, which protective layer includes at least one notch through which at least a portion of at least one bond pad of the semiconductor die is exposed, it is respectfully submitted that none of Yunoki, Dines, or Lee, taken either together or separately, teaches or suggests each and every element of amended independent claim 1.

The allowability of independent claim 1 has already been acknowledged by the Office, as evidenced by the statement regarding the same on page 22 of the outstanding Office Action.

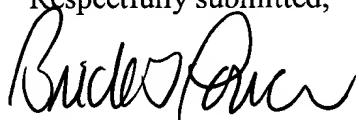
Claims 6 through 9 and 11 are each allowable, among other reasons, as depending either directly or indirectly from claim 1, which is allowable.

Therefore, it is respectfully requested that the 35 U.S.C. § 103(a) rejections of claims 1, 6 through 9, and 11 be withdrawn.

### CONCLUSION

It is respectfully submitted that each of claims 1 through 9, 11 through 14, and 16 through 21 is allowable. An early notice of the allowability of each of these claims and an indication that the above-referenced application has been passed for issuance are respectfully solicited. If any issues preventing allowance of the above-referenced application remain which might be resolved by way of a telephone conference, the Office is kindly invited to contact the undersigned attorney.

Respectfully submitted,



Brick G. Power  
Registration No. 38,581  
Attorney for Applicants  
TRASKBRITT, PC  
P.O. Box 2550  
Salt Lake City, Utah 84110-2550  
Telephone: 801-532-1922

Date: July 29, 2003

BGP/sls:djp  
Document in ProLaw